



CCNY

Docket No. 55855-DIV (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: T. Ho et al.

U.S. SERIAL NO.: 10/719,912

GROUP: 2822

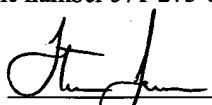
FILED: November 21, 2003

EXAMINER: K. Duong

FOR: METHOD OF FABRICATING A THERMALLY ENHANCED WAFER-LEVEL CHIP SCALE PACKAGE

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to the U.S. Patent & Trademark Office by facsimile number 571-273-8300 on November 7, 2005.

By: 
Steven M. Jensen

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir/Madam:

AMENDMENT

Applicants are in receipt of the Office Action dated September 6, 2005 of the above-referenced application. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.